

Accuracy Analysis of Extraction Methods for Effective Channel Length in Deep-Submicron MOSFETs

Ju-Young Kim, Min-Kwon Choi, and Seonghearn Lee

Abstract—A comparative study of two capacitance methods to measure the effective channel length in deep-submicron MOSFETs has been made in detail. Since the reduction of the overlap capacitance in the accumulation region is smaller than the addition of the inner fringe capacitance at zero gate voltage, the capacitance method removing the parasitic capacitance in the accumulation region extracts a more accurate effective channel length than the method removing that at zero gate voltage.

Index Terms—MOSFET, effective channel length, capacitance, extraction, overlap, fringe

I. INTRODUCTION

The effective channel length L_{eff} is determined by several capacitance methods using the gate-to-channel capacitance C_{GC} . For accurate extraction of C_{GC} , the extrinsic parasitic capacitance C_{p} outside the channel area should be eliminated from the measured gate capacitance C_{G} . Conventionally, the method removing C_{p} determined by C_{G} in the accumulation region at highly negative V_{GS} and another method removing C_{p} at $V_{\text{GS}} = 0$ V have been previously proposed to extract C_{p} [1-4]. By comparing these capacitance methods, it has been reported that the zero V_{GS} method is more accurate than the accumulation method as compared to the resistance method using long-channel MOSFETs with the mask gate length L_{g} of 2 – 10 μm

[1, 2]. However, the resistance method may result in serious errors in the L_{eff} extraction of deep-submicron LDD MOSFETs with halo or pocket implants. As L_{g} is scaled down, C_{p} extraction errors of two methods are largely varied, because the inner fringe capacitance C_{if} contribution to C_{p} at $V_{\text{GS}} = 0$ becomes larger. Thus, the previous comparison results [1-4] may be invalid in deep-submicron MOSFETs.

Therefore, in this paper, using a reference method based on the intrinsic gate-bulk capacitance C_{GBI} measurements that do not need C_{p} extraction with unavoidable errors, the accuracy of two methods to extract L_{eff} in deep-submicron MOSFETs is compared and all internal components of C_{p} are analyzed in detail.

II. EXTRACTION

Using a SOLT(short-open-load-through) calibration method [5], On-wafer S-parameters were measured on bulk N-MOSFETs with 16 gate fingers of different L_{g} ($=0.13, 0.18, 0.25$ and $0.35 \mu\text{m}$) and $2.5 \mu\text{m}$ unit finger width at $V_{\text{DS}} = 0\text{V}$ with varying V_{GS} under common source-bulk configuration. The accurate de-embedding procedure using ‘open’ and ‘short’ test patterns was performed to remove pad and interconnection parasitics from the measured S-parameters [6].

In the low-frequency (LF) region, C_{G} can be determined by:

$$C_{\text{G}} = 2C_{\text{GD}} = (-2/\omega)\text{Imag}(Y_{12})_{\text{LF}} \quad (1)$$

under the assumption of $C_{\text{GD}} = C_{\text{GS}}$ at $V_{\text{DS}} = 0$ V for MOSFETs with the symmetric drain and source structure. To satisfy the inversion condition of $V_{\text{GS}} > V_{\text{TH}} = 0.4$ V,

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$(-2/\omega)\text{Imag}(Y_{12})$ data at $V_{GS} = 0.5$ V in Fig. 1 are used for the extraction of C_G . Fig. 2 shows C_G as a function of V_{GS} at different L_g to be used for extracting C_p .

In the conventional method based on C_p in the accumulation region, C_p values at various L_g are determined from measured C_G at $V_{GS} = -1.5$ V in Fig. 2 under the assumption of the flat band voltage $V_{fb} = -1.5$ V. The values of C_{GC} at various L_g are extracted by subtracting C_p at the same L_g in Fig. 2 from measured C_G at $V_{GS} = 0.5$ V. From the x-intercept of C_{GC} versus L_g at $V_{GS} = 0.5$ V in Fig. 3, ΔL ($= L_g - L_{eff}$) using the accumulation method is extracted to be $0.0509 \mu\text{m}$.

In another conventional method to extract ΔL based on C_p at $V_{GS} = 0$ V, C_{GC} values at various L_g are extracted by subtracting C_p of C_G at $V_{GS} = 0$ V in Fig. 2 from measured C_G at $V_{GS} = 0.5$ V. Using this zero V_{GS} method, ΔL of $0.0757 \mu\text{m}$ that is much larger than that of the accumulation method is determined from the x-intercept of C_{GC} versus L_g at $V_{GS} = 0.5$ V in Fig. 3.

In order to compare the accuracy of these conventional methods [1-4], a reference method [7] based on a V_{GS} -

dependent curve of extracted C_{GBI} to extract the metallurgical channel length L_{met} is performed as follows:

The total gate-bulk capacitance C_{GB} at $V_{DS} = 0$ V is determined by [7]

$$C_{GB} = (1/\omega)\text{Imag}(Y_{11} + 2Y_{12})_{LF} \quad (2)$$

Since C_{GBI} is masked at $V_{GS} > V_{TH}$, the extrinsic gate-bulk capacitance C_{GBE} is accurately extracted by measuring C_{GB} of Eq. (2) at $V_{GS}=0.5$ V $> V_{TH}=0.4$ V. Thus, C_{GBI} at $V_{GS}<V_{TH}$ is determined by $C_{GB} - C_{GBE}$. The V_{GS} -dependent data of the source-drain overlap and depletion length $L_{OD}(=2L_{ov}+2L_{de})$ where L_{ov} is the source/drain overlap length and L_{de} is the source/drain depletion length are extracted from the x-intercepts of the regression lines for C_{GBI} versus L_g in Fig. 4. The metallurgical channel length reduction ΔL_{met} ($= L_g - L_{met}$) is determined by $2L_{ov} = 0.0577 \mu\text{m}$ at $V_{GS} = -1.5$ V where the decreasing rate of L_{OD} with increasing $|V_{GS}|$ is maximum [7]. This value of $V_{GS} = -1.5$ V is the boundary voltage between the accumulation and

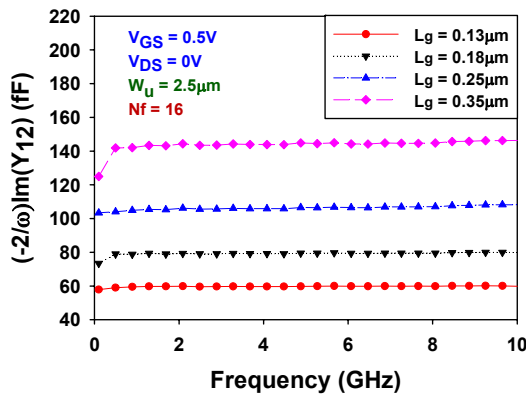


Fig. 1. Measured $(-2/\omega)\text{Imag}(Y_{12})$ vs. frequency at various L_g .

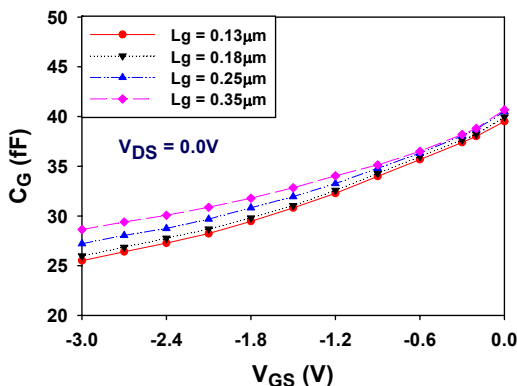


Fig. 2. The V_{GS} -dependence of C_G at various L_g .

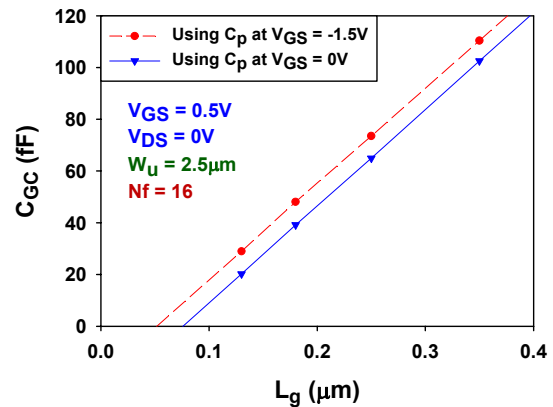


Fig. 3. Extracted C_{GC} versus L_g using conventional methods.

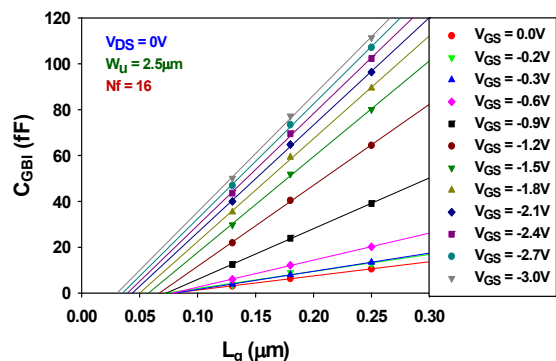


Fig. 4. Extraction data of C_{GBI} versus L_g at different V_{GS} .

depletion regions, verifying the previous assumption of $V_{fb} = -1.5$ V. This method is used as a reference for the accuracy analysis because C_p extraction with unavoidable errors is not required.

As a result, much closer ΔL to ΔL_{met} is obtained for the accumulation method than the zero V_{GS} one. This indicates that the accumulation method is more accurate for extracting L_{eff} in deep-submicron MOSFETs than the zero V_{GS} one.

III. ANALYSIS

In order to find the exact cause for the better accuracy of the accumulation method than the zero V_{GS} one, all internal components of C_p determined by these methods are accurately extracted.

In the inversion region, C_p is defined as $C_{ov} + C_{of}$ where C_{ov} is the source-drain overlap capacitance and C_{of} is the outer fringing capacitance. Using the linear regression of C_G versus L_g , C_p is extracted by finding C_G at $L_g = 2L_{ov}$ where C_{GC} disappears. Thus, C_p at $V_{GS} = 0.5$ V is extracted to be 32.5 fF in Fig. 5. As shown in Fig. 2, C_G increases slightly with increasing L_g at negative V_{GS} , because of the increase of C_{of} . Thus, in Fig. 5, C_p values at $L_g = 2L_{ov}$ to keep the same C_{of} as that in the inversion region are extracted to be 30.0 fF and 39.3 fF at $V_{GS} = -1.5$ V and $V_{GS} = 0$ V, respectively.

Since C_{of} is independent of V_{GS} , the C_p variation of $\Delta C_p = 2.5$ fF from $V_{GS} = 0.5$ V to $V_{GS} = -1.5$ V is attributed to the decrease of C_{ov} caused by the expanded depletion width of n^- overlap region at more negative V_{GS} . However, the inner fringe capacitance C_{if} is added to $C_p (=C_{ov} + C_{of})$

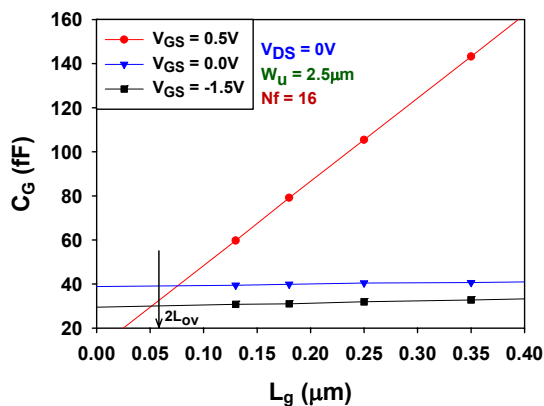


Fig. 5. Measured data and regression line of C_G versus L_g at different V_{GS} .

at $V_{GS} = 0$ V, because the bottom of the gate is not screened from the inner side wall of the source/drain overlap regions due to the absence of the inversion or accumulation layers under the gate oxide [8]. Since C_{ov} keeps constant at positive V_{GS} due to the accumulation of n^- overlap region, ΔC_p of 6.7 fF from $V_{GS} = 0.5$ V to $V_{GS} = 0$ V is due to the addition of C_{if} at $V_{GS} = 0$ V. Thus, the error of the accumulation method due to the C_{ov} reduction is smaller than that of the zero V_{GS} method due to the addition of C_{if} .

IV. CONCLUSIONS

As compared with the C_{GBI} method without C_p extraction with unavoidable errors, it is found that the accumulation method is more accurate in extracting L_{eff} in deep-submicron MOSFETs than the zero V_{GS} one. This result is justified by analyzing all internal components of extrapolated C_p at $L_g = 2L_{ov}$.

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